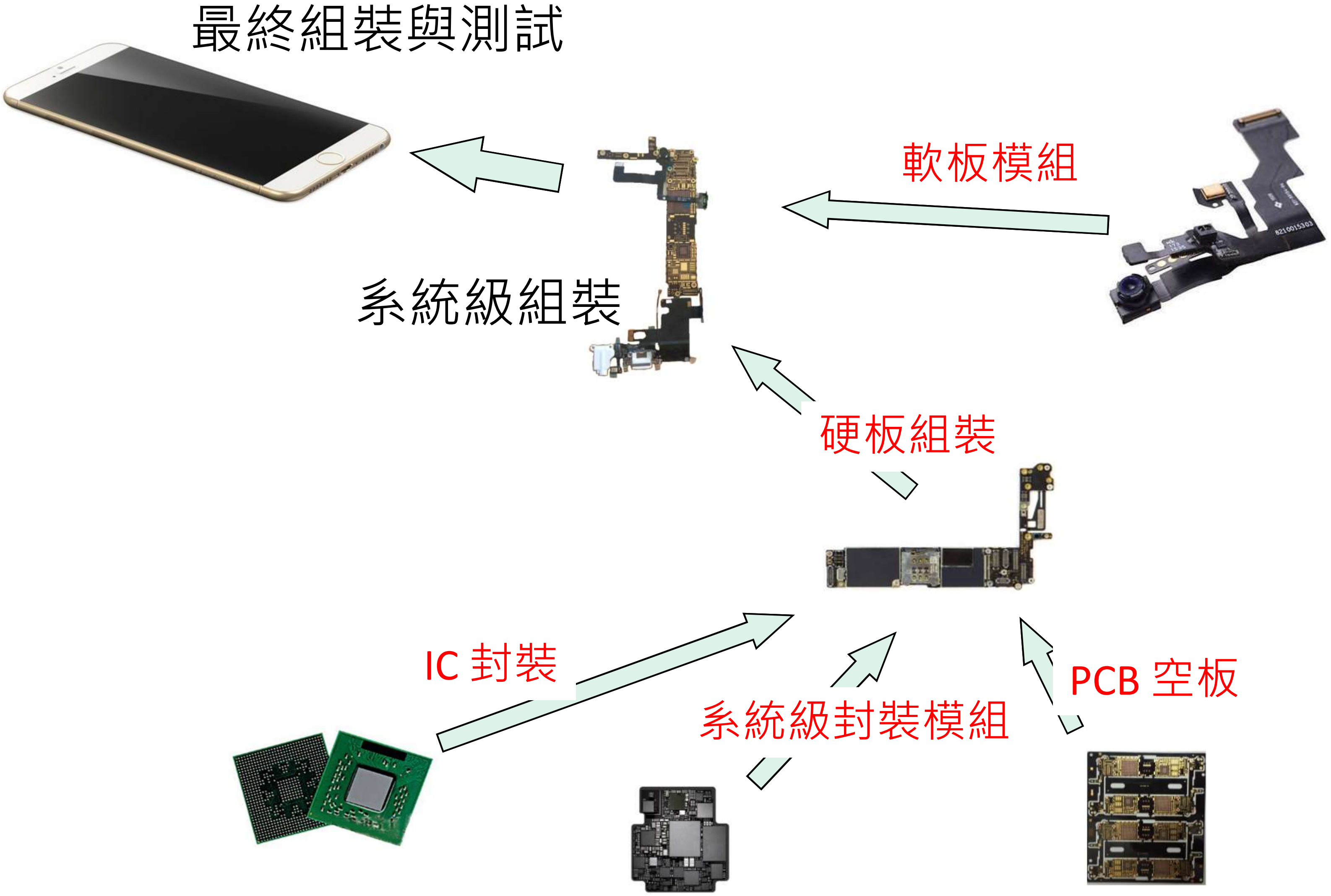
景碩科技股份有限公司
Kinsus Interconnect Technology Corp.

Aug. 2020

IC 封裝技術
IC Packaging Technology

電子產品構裝的各個層次



最終組裝與測試

軟板模組

系統級組裝

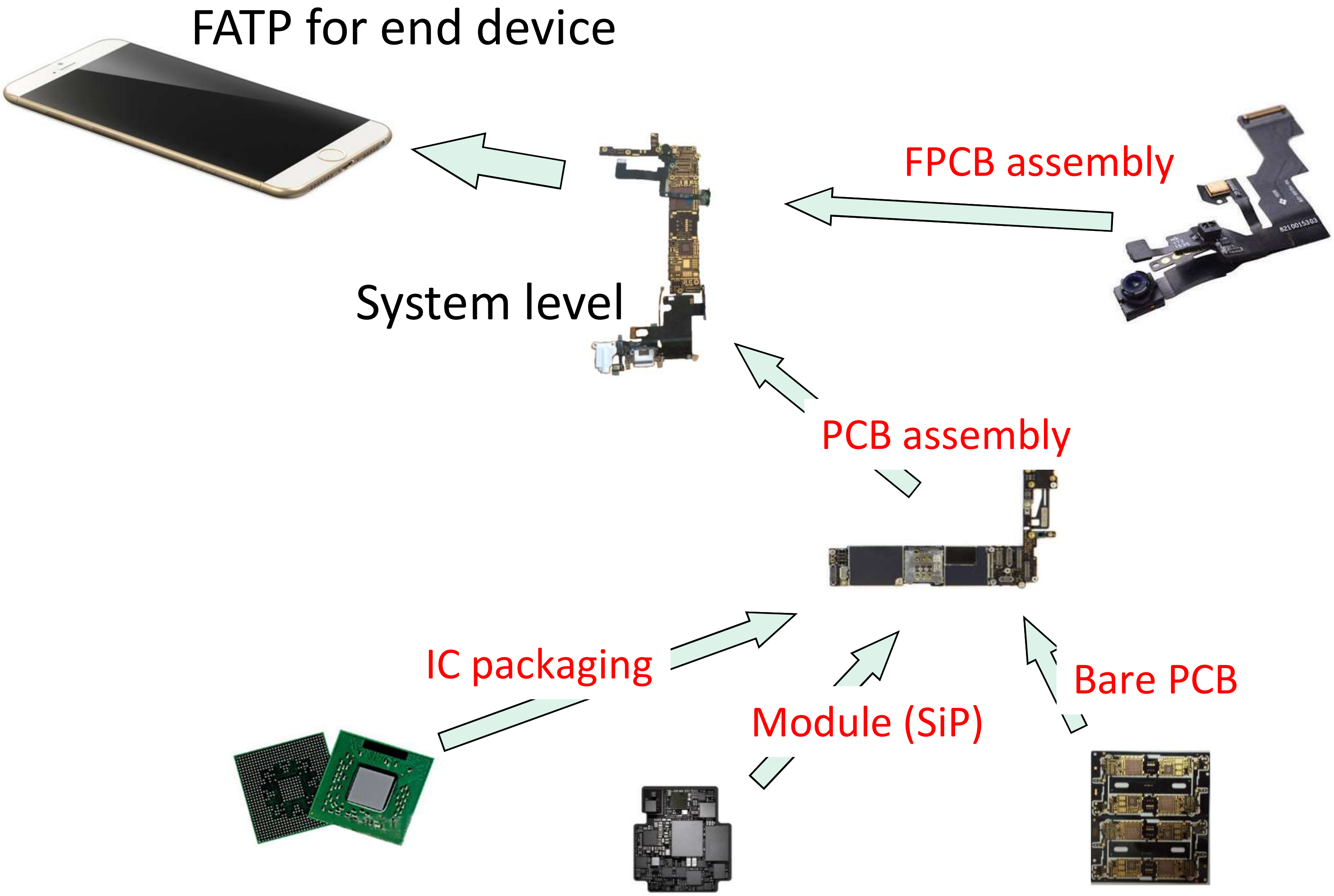
硬板組裝

IC 封裝

系統級封裝模組

PCB 空板

Levels of Assembly



FATP for end device

System level

FPCB assembly

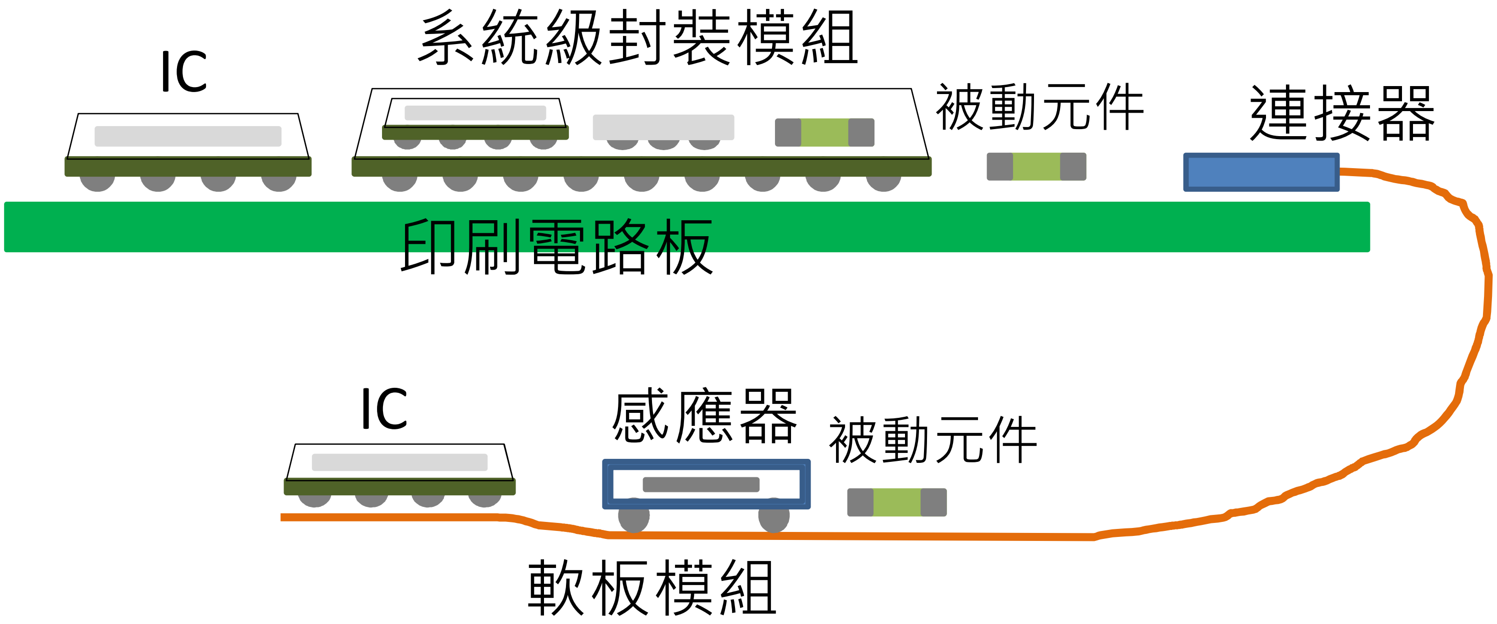
PCB assembly

IC packaging

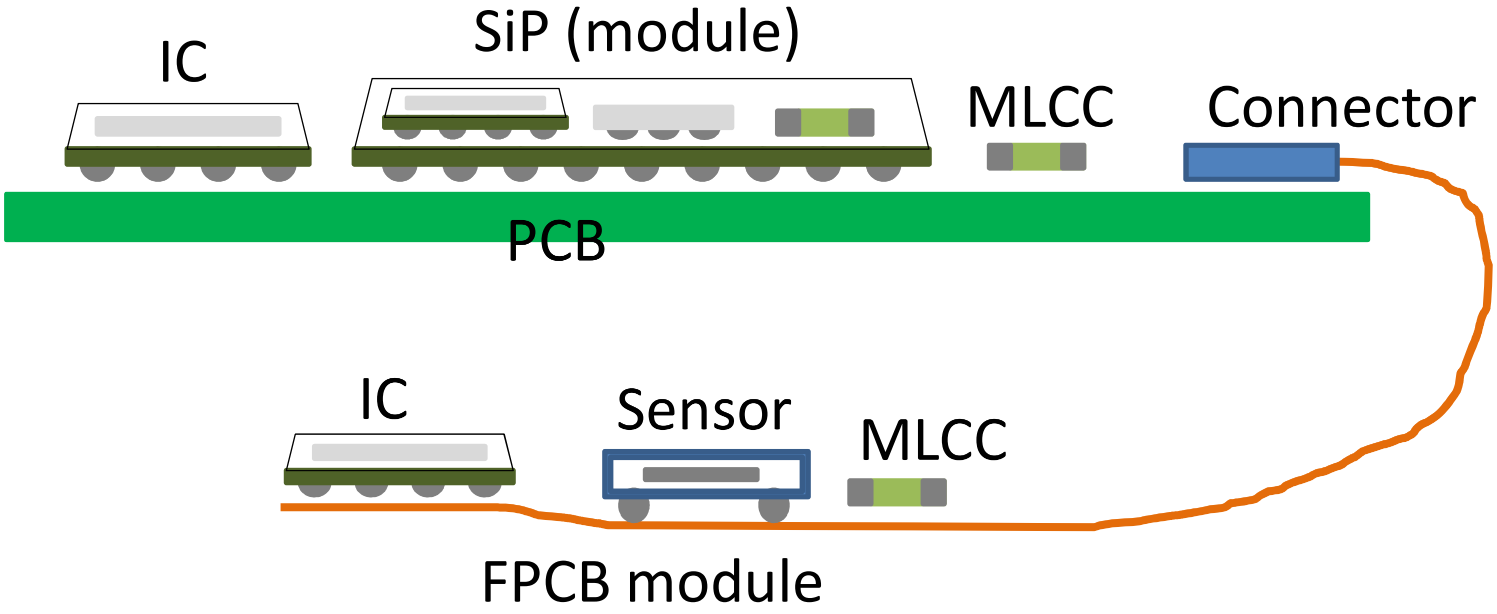
Module (SiP)

Bare PCB

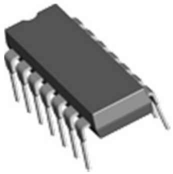
電子產品的組裝結構



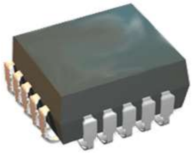
Basic structure of electronic devices

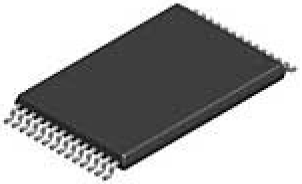


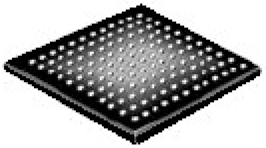
各種形式的IC 封裝


DIP

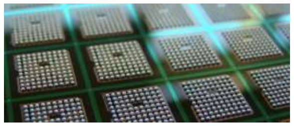

QFP

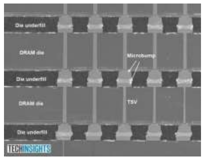

PLCC

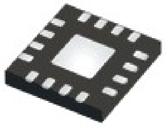

TSOP


PBGA/
Flip-Chip BGA

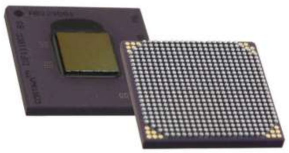

CSP

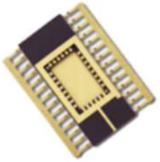

WLP


TSV


QFN

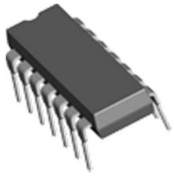

DFN


Ceramic BGA


Ceramic chip

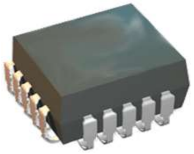
市場規模: 2016 年2,520 億顆, 其中 719 億顆為 BGA 封裝

Different types of IC packaging

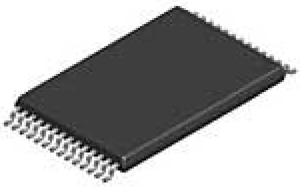


DIP

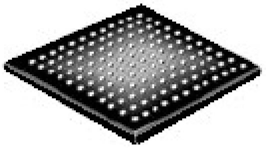
QFP



PLCC

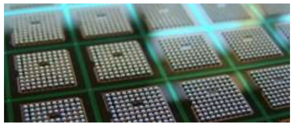


TSOP

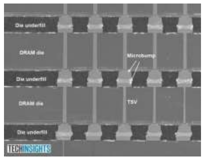


PBGA/
Flip-Chip BGA

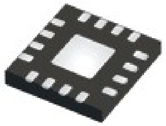
CSP



WLP

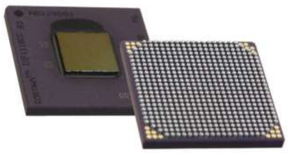


TSV

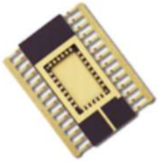


QFN

DFN



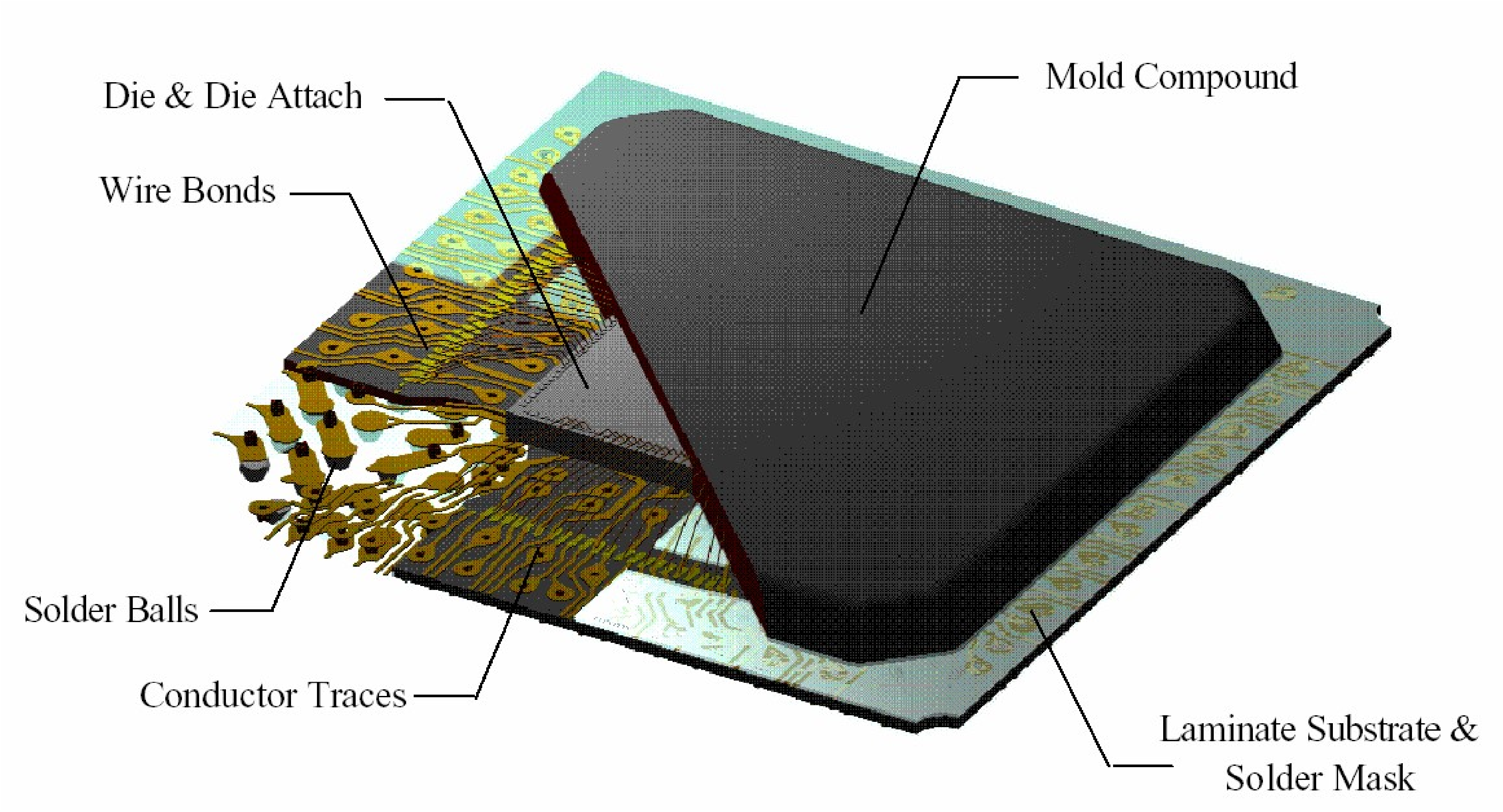
Ceramic BGA



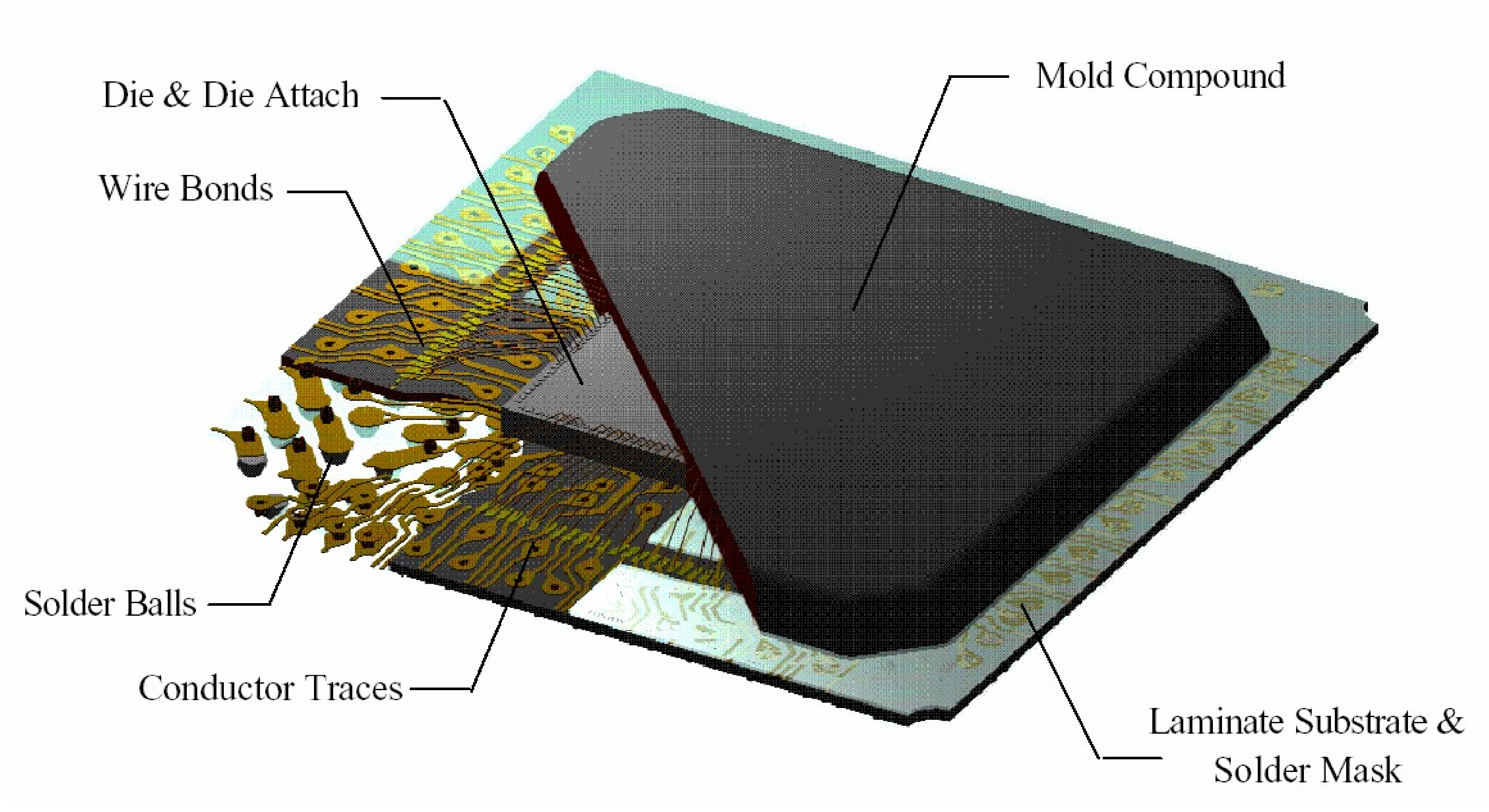
Ceramic chip

Market size : 252 Billion units in 2016, 71.9 Billion units in BGA substrates

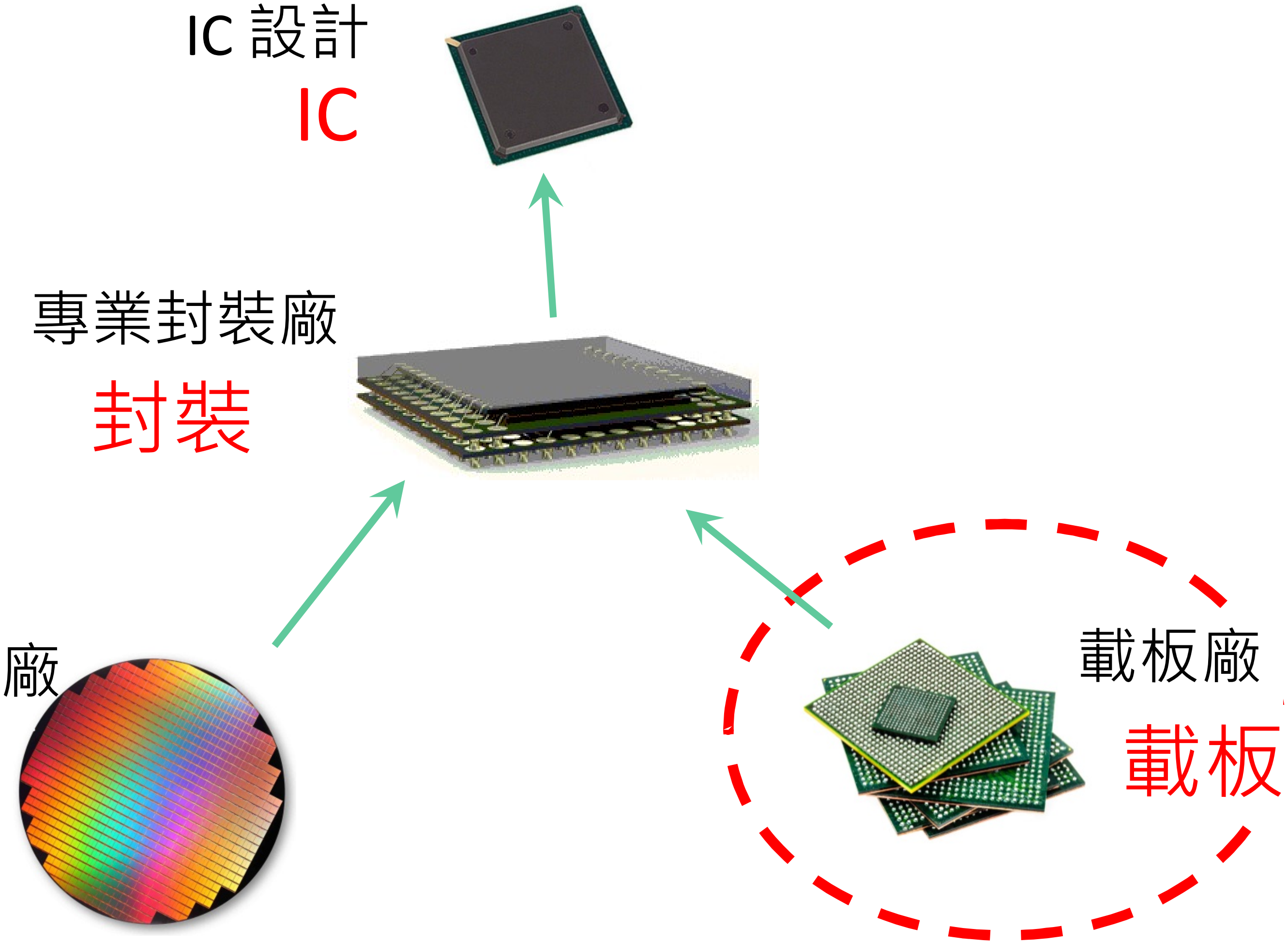
IC 結構


Die & Die Attach
Wire Bonds
Mold Compound
Solder Balls
Conductor Traces
Laminate Substrate &
Solder Mask

What Substrate Makers do?



IC 半導體上下游供應鏈關係



IC 設計

IC

專業封裝廠

封裝

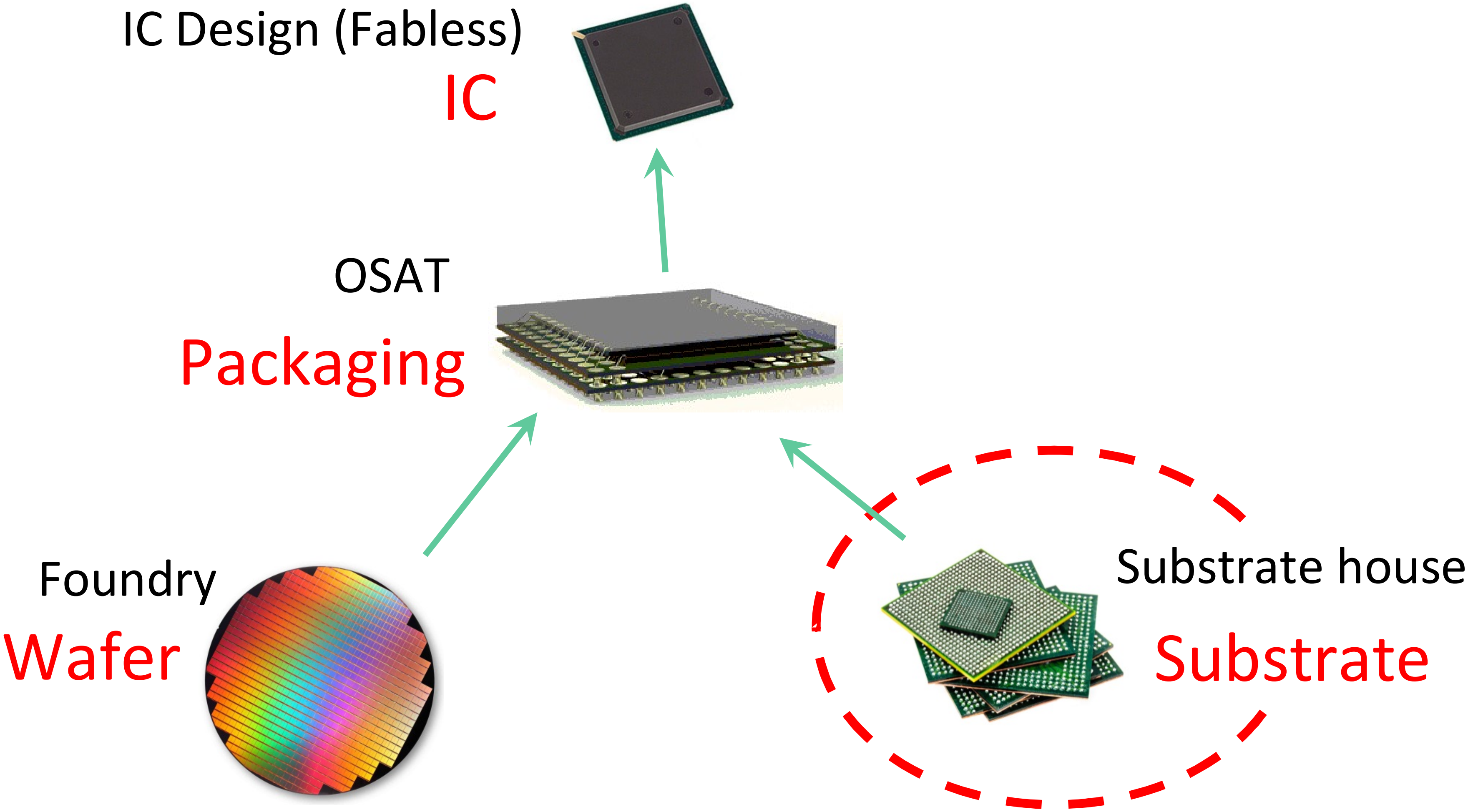
晶圓製造廠

晶圓

載板廠

載板

IC Manufacturing Supply Chain



IC Design (Fabless)

IC

OSAT

Packaging

Foundry

Wafer

Substrate house

Substrate

About Kinsus

基本資料

- 公司成立 2000

  台股上市掛牌 2004

- 資本額 : 新台幣 45.12 億元

- 廠區 :

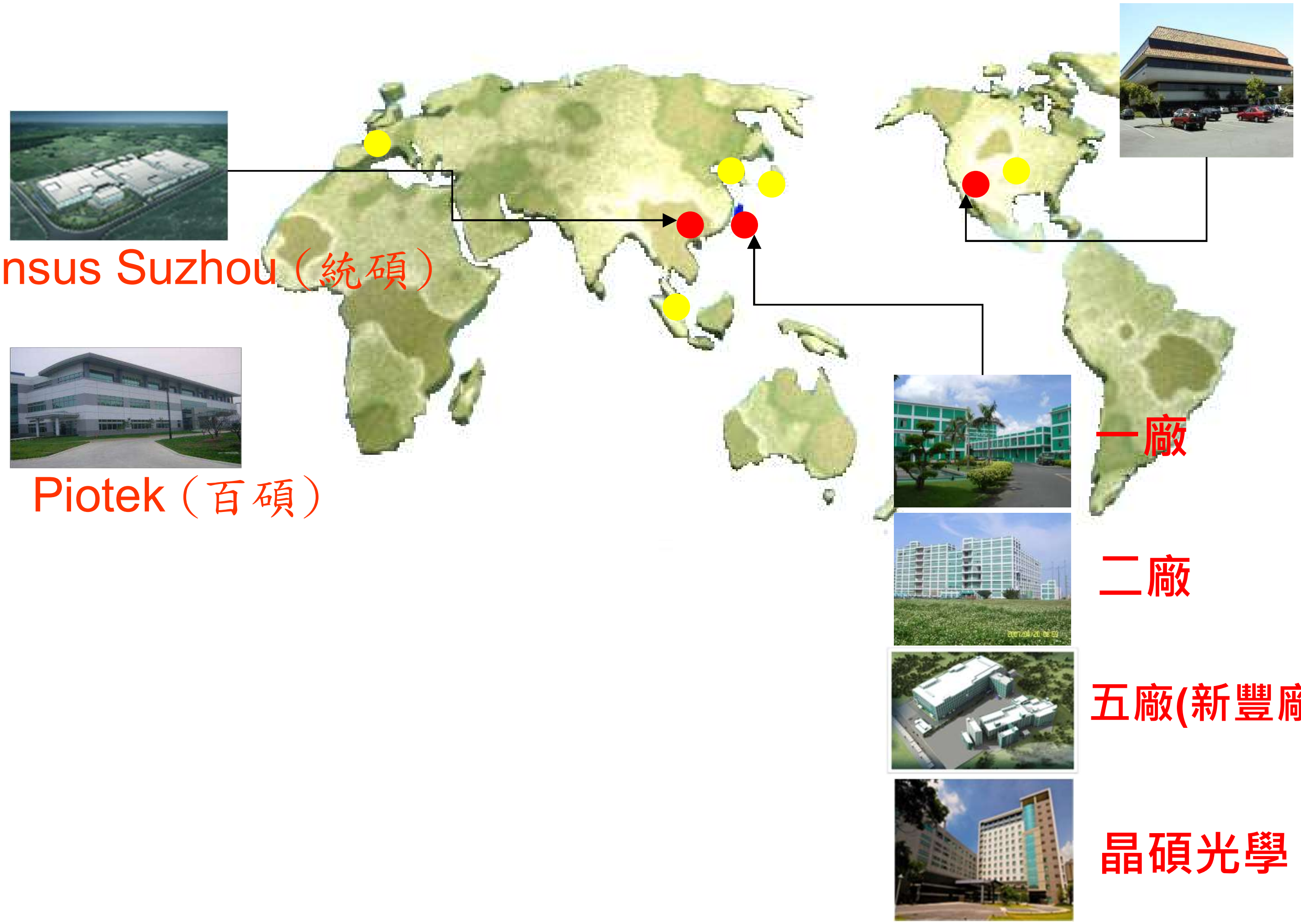
總部	- 新屋 / 台灣
IC 載板	- 一廠 及 二廠
	- 新豐廠 (五廠)
Kinsus USA	- Santa Clara / California
統碩科技	- 蘇州 / 中國
百碩電腦	- 蘇州 / 中國
晶碩光學	- 桃園 / 台灣

Basic Information

- Established in September 2000
  IPO at TWSE in November 2004
- Capital : US$ 146 Million (NT$ 4.512 Billion)
- Campus :

Headquarters	- Xin Wu / Taiwan
IC substrates	- Plant I & II
	- Xing-Feng plant (Plant V)
Kinsus USA	- Santa Clara / California
Kinsus China	- Suzhou / China
Piotek	- Suzhou / China
PegaVision	- Taoyuan / Taiwan

位置



Kinsus Suzhou（統碩）

Piotek（百碩）

美國子公司

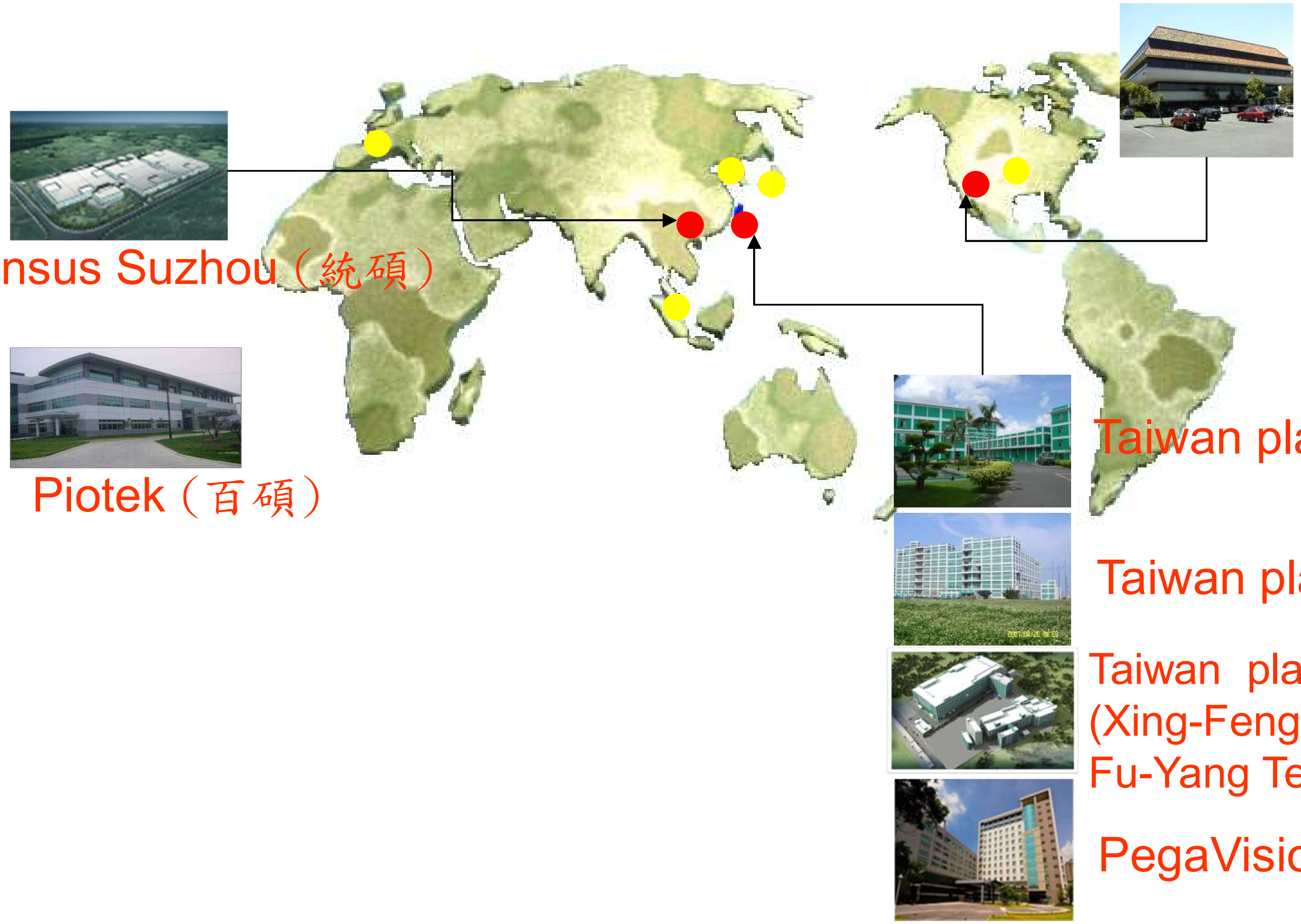
一廠

二廠

五廠(新豐廠)

晶碩光學

Locations



Kinsus USA

Kinsus Suzhou（統碩）

Piotek（百碩）

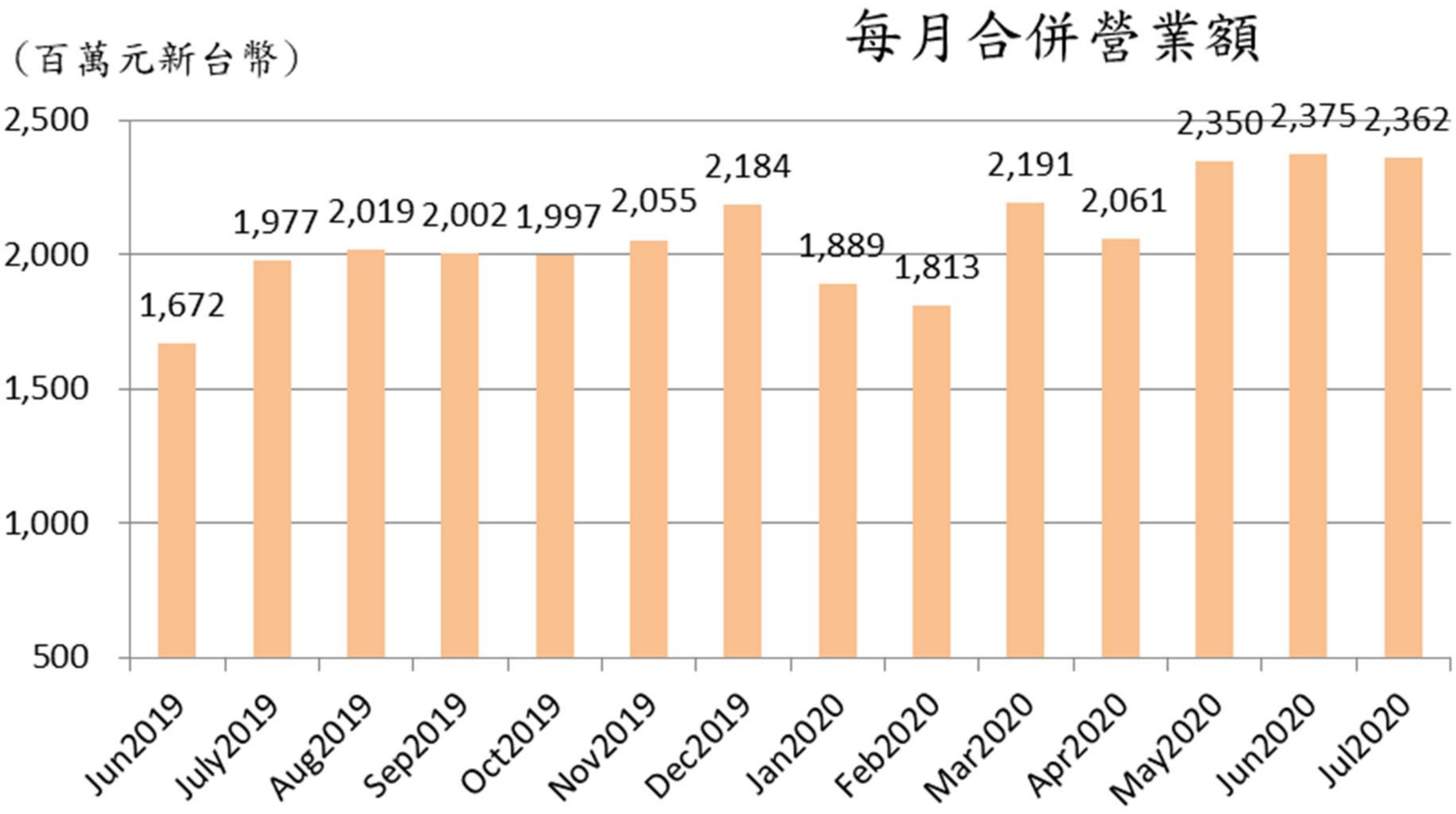
Taiwan plant I

Taiwan plant II

Taiwan plant V
(Xing-Feng plant)
Fu-Yang Technology

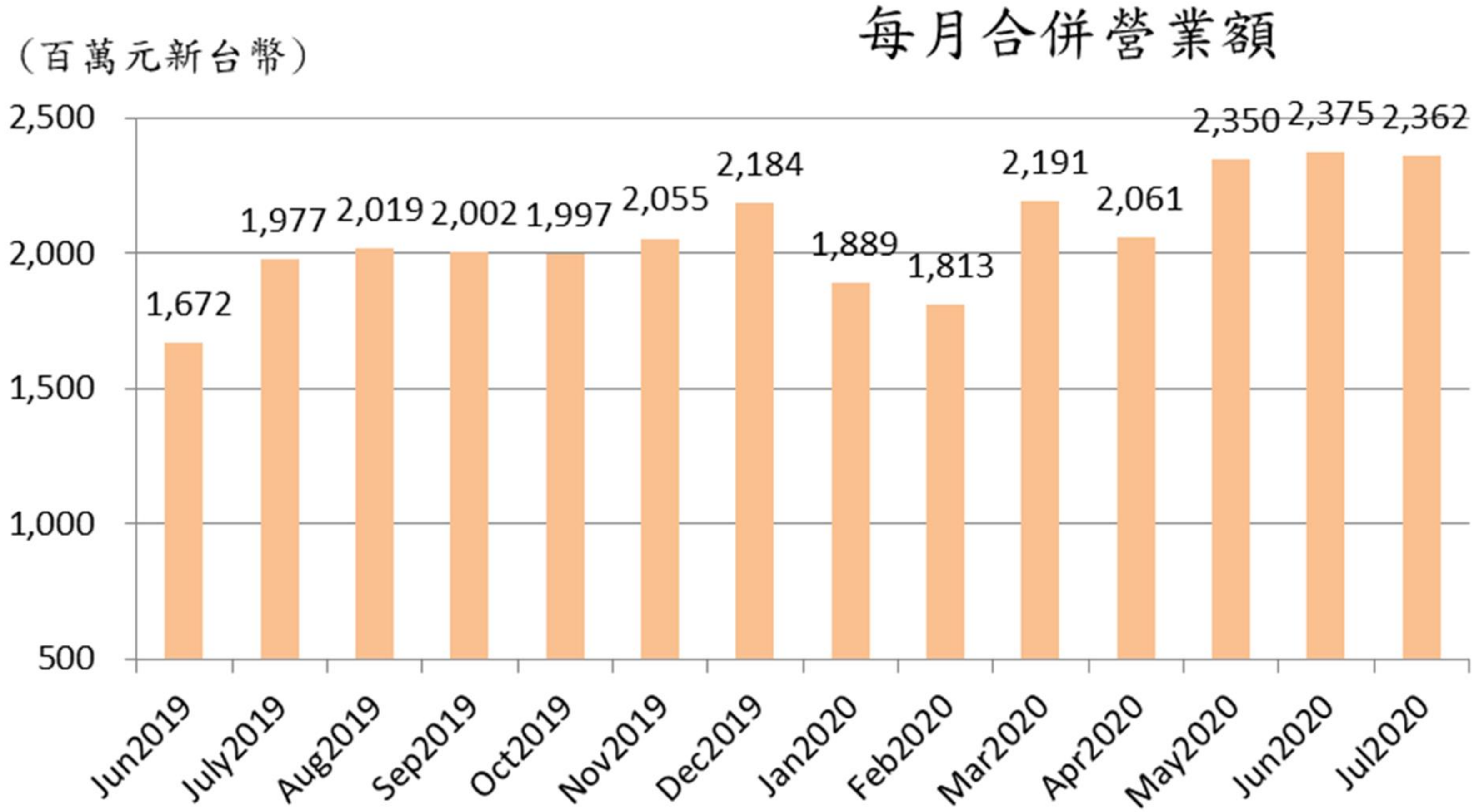
PegaVision

每月營業額



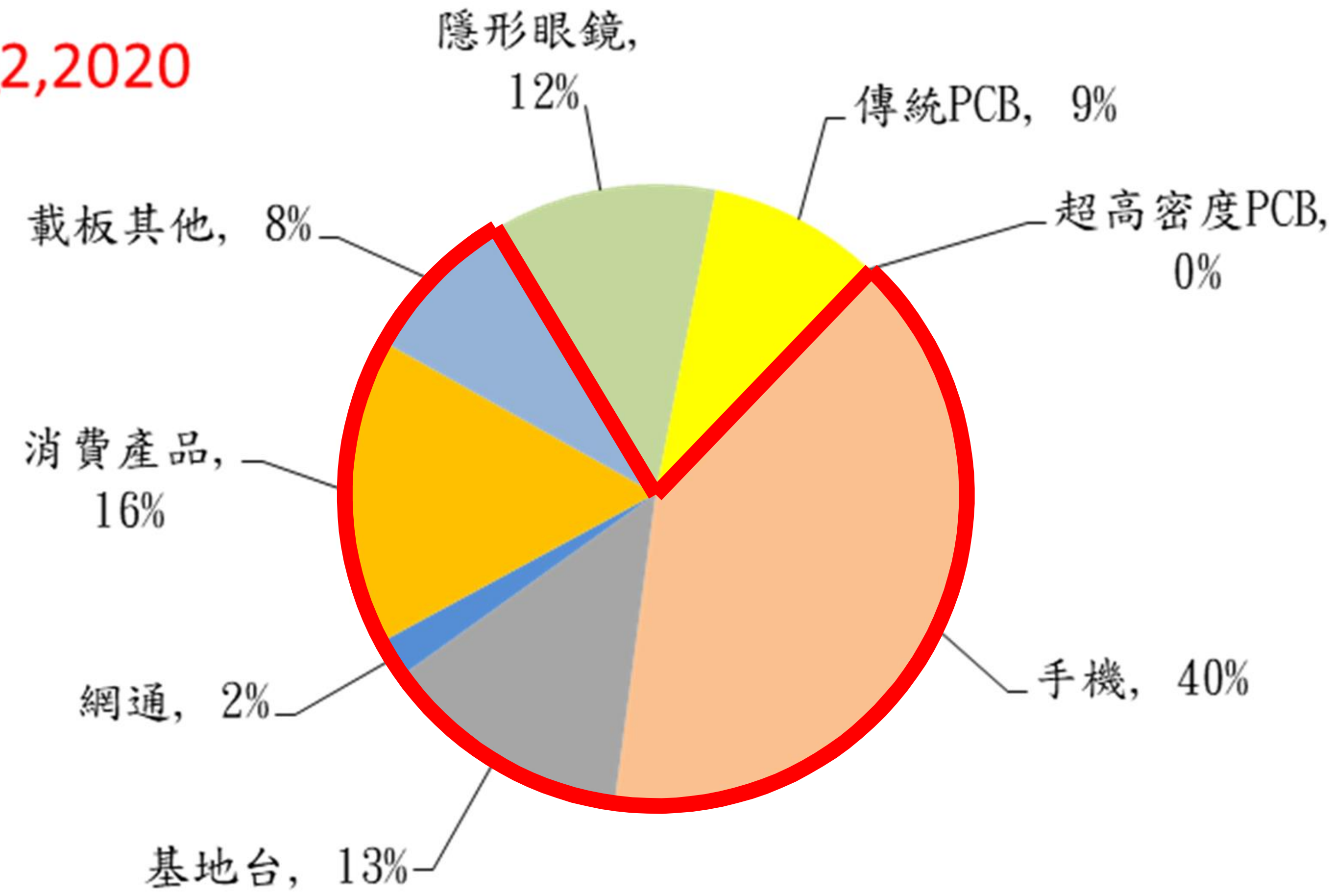
每月合併營業額
(百萬元新台幣)
2,500
2,000
1,500
1,000
500
1,672
1,977
2,019
2,002
1,997
2,055
2,184
1,889
1,813
2,191
2,061
2,350
2,375
2,362
Jun2019
July2019
Aug2019
Sep2019
Oct2019
Nov2019
Dec2019
Jan2020
Feb2020
Mar2020
Apr2020
May2020
Jun2020
Jul2020

Monthly Revenue

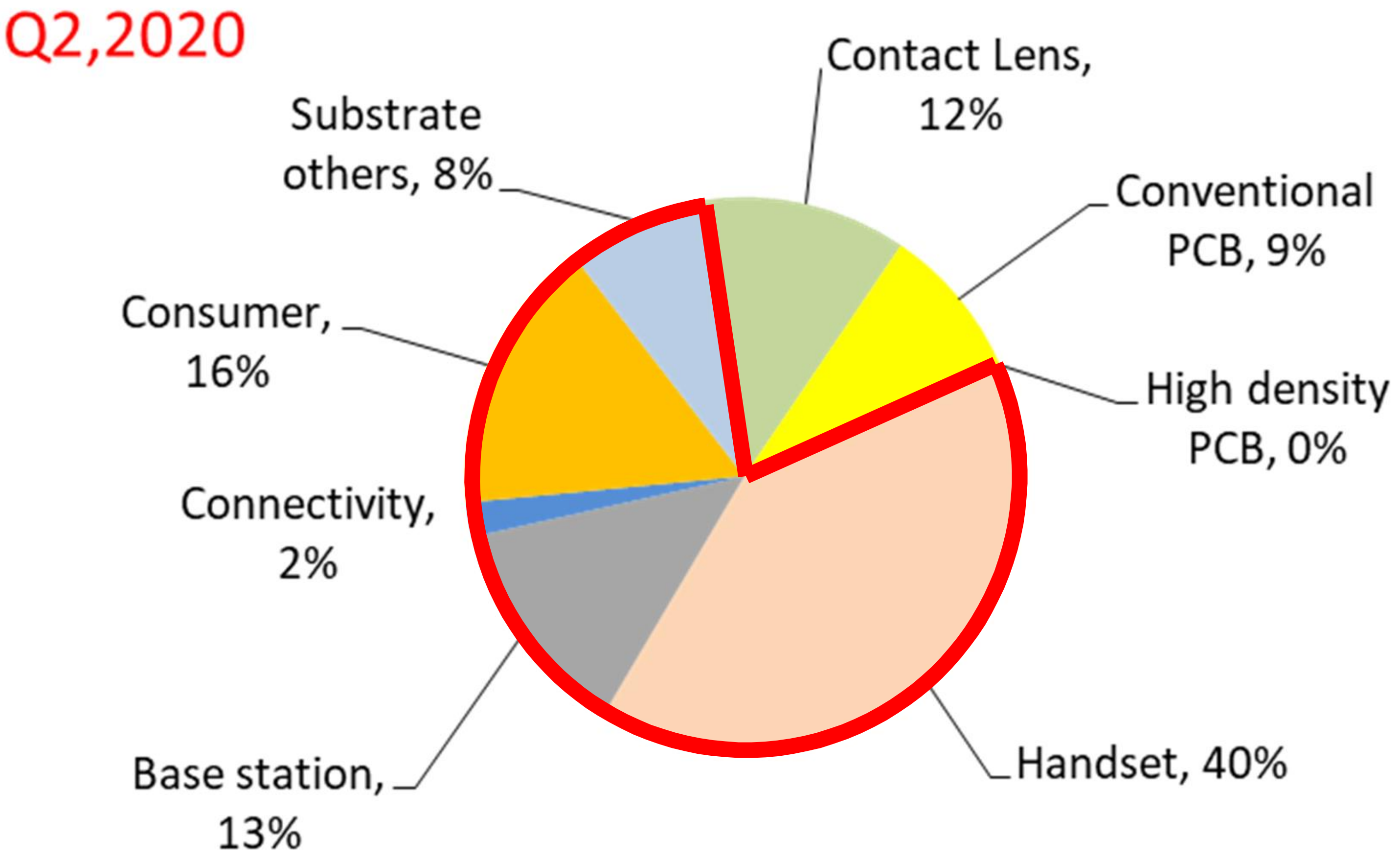


產品組合

Q2,2020



Product mix



Q2,2020
Contact Lens, 12%
Conventional PCB, 9%
High density PCB, 0%
Handset, 40%
Base station, 13%
Connectivity, 2%
Consumer, 16%
Substrate others, 8%

Thank you